

N-Ch 200V Fast Switching MOSFETs
Description

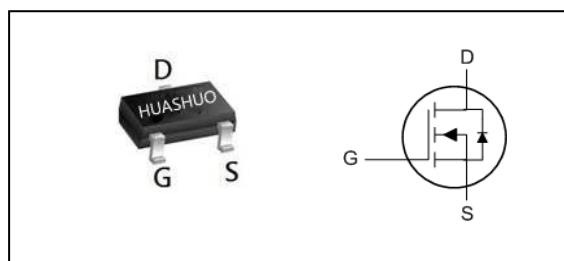
The HSS1N20B is the high cell density trenched N-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

The HSS1N20B meets the RoHS and Green Product requirement with full function reliability approved.

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Product Summary

V _{DS}	200	V
R _{DSON,typ}	2.5	Ω
I _D	0.8	A

SOT-23L Pin Configuration

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	200	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	0.8	A
I _{DM}	Pulsed Drain Current ²	7	A
P _D @T _A =25°C	Total Power Dissipation ³	0.8	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	42	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	200	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =0.8A	---	2.5	3.0	Ω
		V _{GS} =4.5V , I _D =0.8A	---	2.6	3.3	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	---	3.0	V
I _{bss}	Drain-Source Leakage Current	V _{DS} =200V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =200V , V _{GS} =0V , T _J =55°C	---	---	5	
I _{css}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =15V , I _D =2A	---	9	---	S
Q _g	Total Gate Charge (10V)	V _{DS} =100V , V _{GS} =10V , I _D =2A	---	10	---	nC
Q _{gs}	Gate-Source Charge		---	2.1	---	
Q _{gd}	Gate-Drain Charge		---	4.8	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =100V , V _{GS} =10V , R _G =2.5Ω	---	8	---	ns
T _r	Rise Time		---	13	---	
T _{d(off)}	Turn-Off Delay Time		---	11	---	
T _f	Fall Time		---	18	---	
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0V , f=1MHz	---	450	---	pF
C _{oss}	Output Capacitance		---	78	---	
C _{rss}	Reverse Transfer Capacitance		---	4	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _s	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current	---	---	0.8	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _s =1A , T _J =25°C	---	---	1.2	V

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

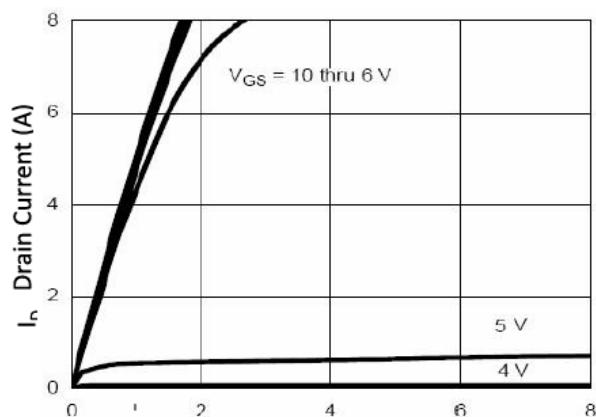


Figure 1 Output Characteristics

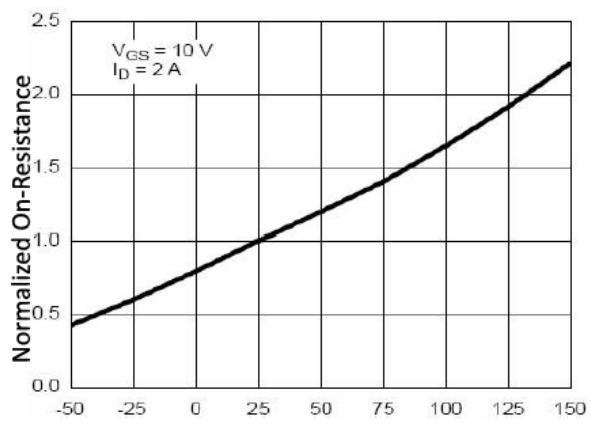


Figure 4 Rdson-JunctionTemperature

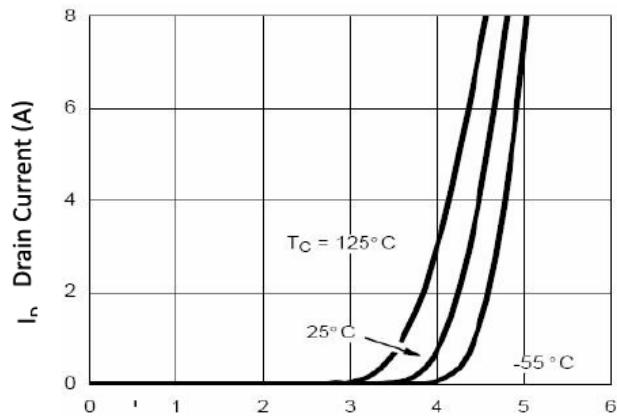


Figure 2 Transfer Characteristics

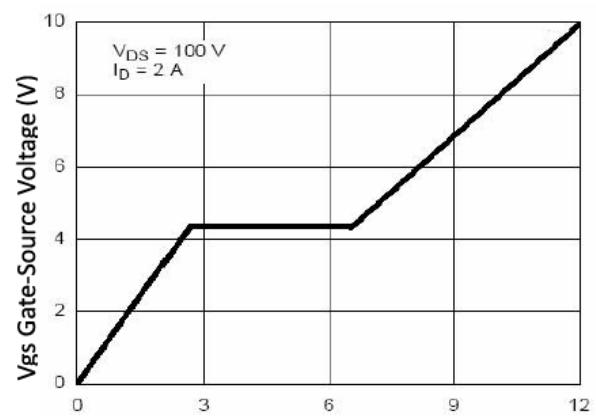


Figure 5 Gate Charge

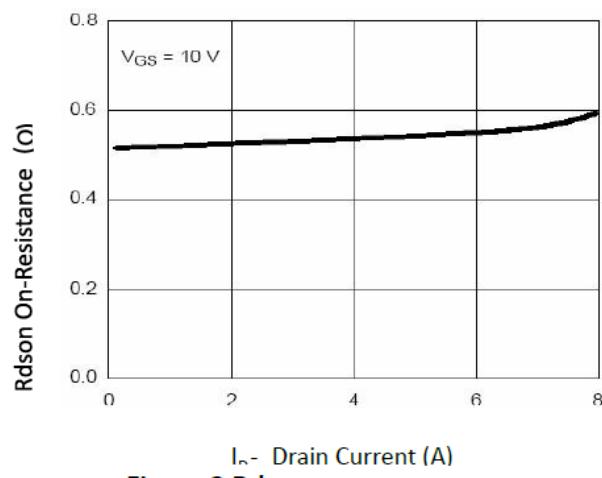


Figure 3 Rdson-Drain Current

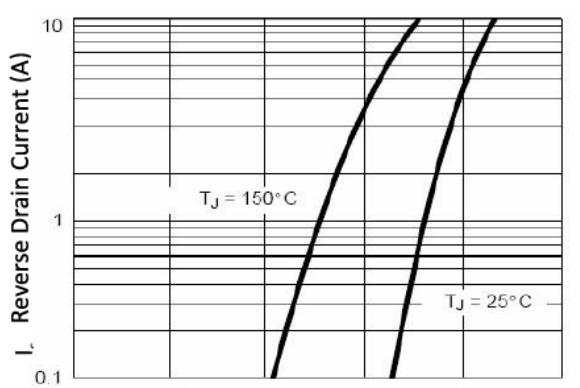


Figure 6 Source-Drain Diode Forward



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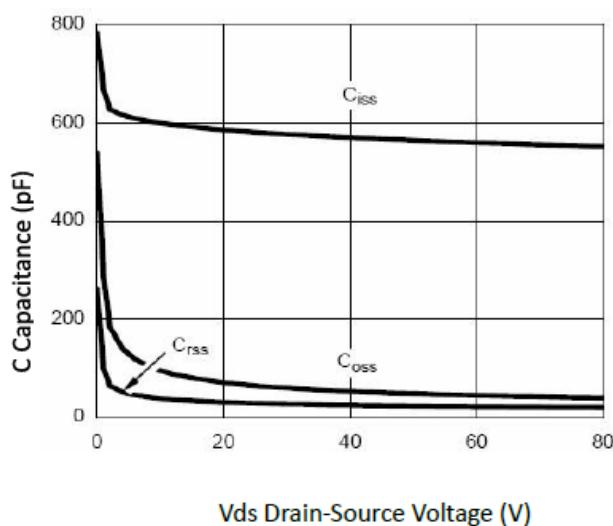


Figure 7 Capacitance vs Vds

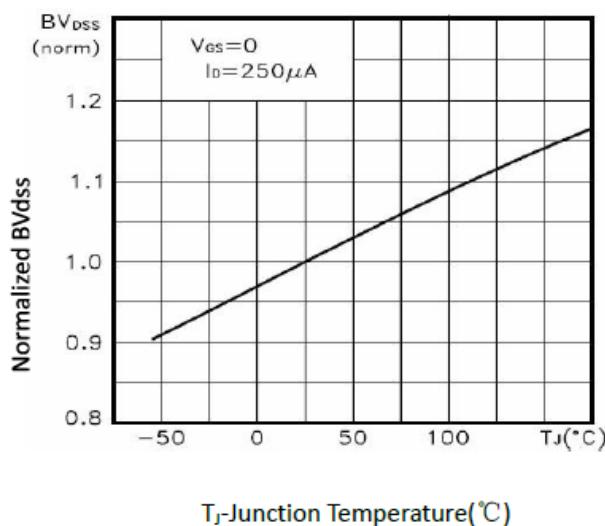


Figure 9 BV_{dss} vs Junction Temperature

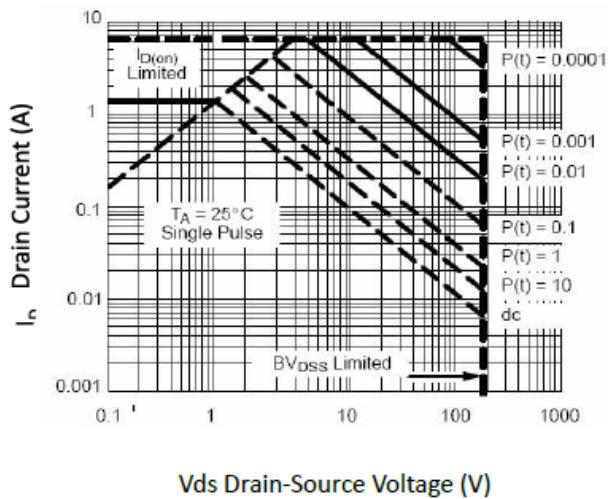


Figure 8 Safe Operation Area

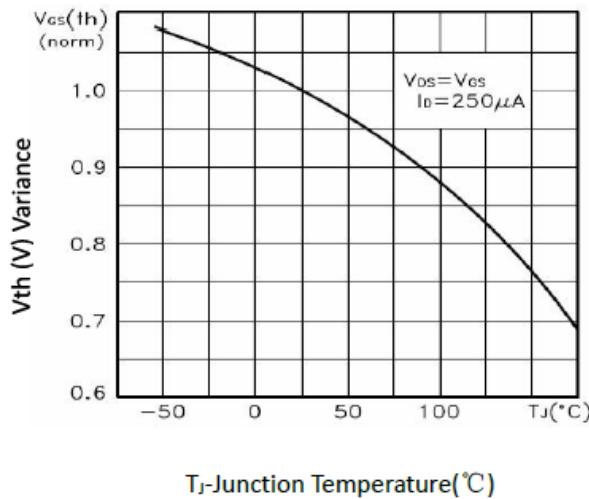


Figure 10 V_{GS(th)} vs Junction Temperature

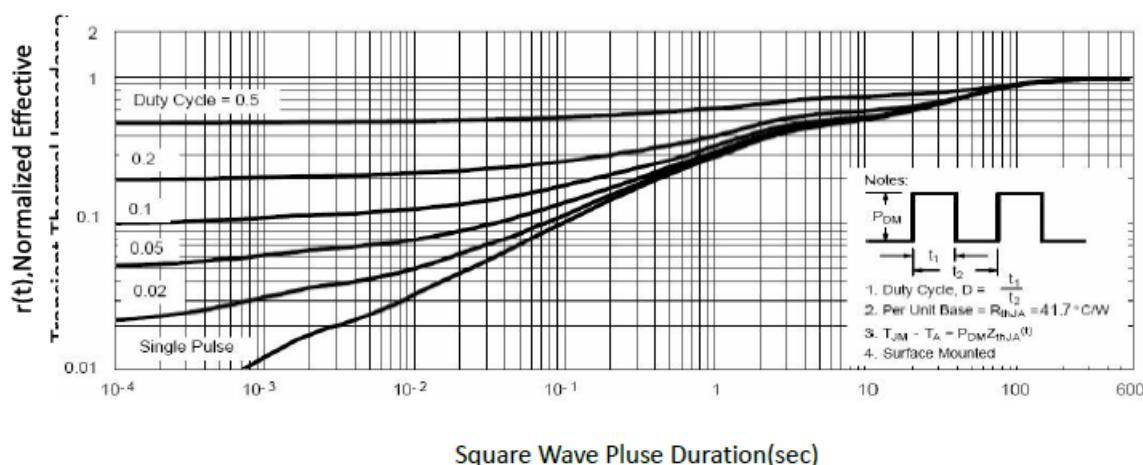


Figure 11 Normalized Maximum Transient Thermal Impedance

Ordering Information

Part Number	Package code	Packaging
HSS1N20B	SOT-23L	3000/Tape&Reel

